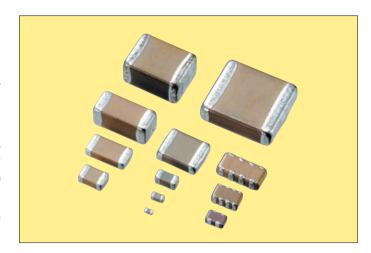
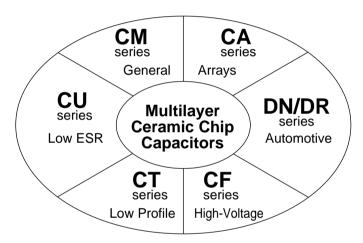


Kyocera's series of Multilayer Ceramic Chip Capacitors are designed to meet a wide variety of needs. We offer a complete range of products for both general and specialized applications, including the general-purpose CM series, the high-voltage CF series, the low profile CT series, and the DN series for automotive uses.

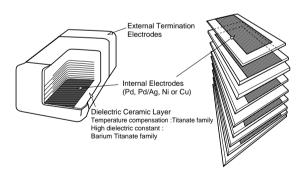
#### **Features**

- We have factories worldwide in order to supply our global customer bases quickly and efficiently and to maintain our reputation as one of the highest-volume producers in the industry.
- All our products are highly reliable due to their monolithic structure of high-purity and superfine uniform ceramics and their integral internal electrodes.
- By combining superior manufacturing technology and materials with high dielectric constants, we produce extremely compact components with exceptional specifications.
- Our stringent quality control in every phase of production from material procurement to shipping ensures consistent manufacturing and super quality.
- Kyocera components are available in a wide choice of dimensions, temperature characteristics, rated voltages, and terminations to meet specific configurational requirements.

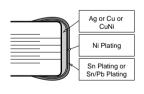




### **Structure**



Nickel Barrier Termination Products



### Tape and Reel



**Bulk Cassette** 



Please contact your local AVX, Kyocera sales office or distributor for specifications not covered in this catalog.

Our products are continually being improved. As a result, the capacitance range of each series is subject to change without notice. Please contact an sales representative to confirm compatibility with your application.



Kyocera Ceramic Chip Capacitors are available for different applications as classified below:

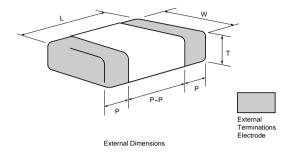
Series	Dieletric Options	Typical Applications	Features	Terminations	Available Size (EIA)
СМ	COG (NP0) X5R X7R X6S X7S Y5V NTC*	General Purpose	Wide Cap Range	Nickel Barrier	0201, 0402, 0603 0805, 1206, 1210 1812, 2211, 2220
CF	C0G (NP0) X7R	High Voltage & Power Circuits	High Voltage 250VDC, 630VDC 1000VDC, 2000VDC 3000VDC, 4000VDC	Nickel Barrier	0805, 1206, 1210 1812, 2208, 1808 2220
СТ	C0G (NP0) X5R X7R Y5V	PLCC (Decoupling)	Low Profile	Nickel Barrier	0402, 0603, 0805 1206, 1210
*DN/DR	C0G (NP0) U (750) X7R	Automotive	Thermal shock Resistivity High Reliability	Nickel Barrier	0603, 0805, 1206
CU	C0G (NP0)	RF Circuit	Low ESR	Nickel Barrier	0402, 0603
CA	C0G (NP0) X5R	Digital Signal Pass line	Reduction in Placing Costs	Nickel Barrier	0405, 0508, 0612

<sup>\*</sup> NTC: Negative Temperature coefficient types are available on request.

<sup>\*</sup> DN Series: Silver Palladium termination is available on request. \* CA Series: X7R, Y5V are available on request.



# **Dimensions**



Tape & Reel

rape o	k Meei							
Size	EIA CODE	EIAJ CODE			Dimensi	ions (mm)		
Oize	LIA GODE	LIAU GODE	L	w	P min	P max	P to P min	T max
03	0201	0603	0.6±0.03	0.3±0.03	0.10	0.20	0.20	0.33
05	0402	1005	1.0±0.05	0.5±0.05	0.15	0.35	0.30	0.55
105	0603	1608	1.6±0.10	0.8±0.10	0.20	0.60	0.50	0.90
21	0805	2012	2.0±0.10	1.25±0.10	0.20	0.75	0.70	1.35
316	1206	3216	3.2±0.20	1.60±0.15	0.30	0.85	1.40	1.75
32	1210	3225	3.2±0.20	2.50±0.20	0.30	1.00	1.40	2.70
42	1808	4520	4.5±0.20	2.00±0.20	0.15	0.85	2.60	2.20
43	1812	4532	4.5±0.30	3.20±0.20	0.30	1.10	2.00	3.0
52	2208	5720	5.7±0.40	2.00±0.20	0.15	0.85	4.20	2.20
53	2211	5728	5.7±0.40 2.80±0.20		0.15	0.85	4.20	2.80
55	2220	5750	5.7±0.40	5.00±0.40	0.30	1.40	2.50	2.70

# **Bulk Cassette**

Size	FIA CODE	EIAJ CODE		w	-	ı	P	P to P
Size	EIA CODE		L	VV	·	min	max	min
05	0402	1005	1.0±0.05	0.5±0.05	0.5±0.05	0.15	0.35	0.30
105	0603	1608	1.6±0.07	0.8±0.07	0.8±0.07	0.20	0.60	0.50
21	0805	2012	2.0±0.1	1.25±0.1	0.6±0.1/1.25±0.1	0.20	0.75	0.70

<sup>CT21, CT316: (L) 3.2±0.2mm and (W)1.6±0.2mm

T (Thickness) depends on capacitance value.
Standard thickness is shown on the appropriate product pages.

DR series 105, 21 size (L)(W)(T) Tolerance ±0.15mm

CA series (please refer page 19)</sup> 



KYOCERA PART NUMBER:	CM 21 X7R 104 K 50 A T
SERIES CODE	
CM = General Purpose CA = Capacitor Arrays CF = High Voltage CU = Low ESR CT = Low Profile DN/DR = Automotive	
SIZE CODE —	
05     =     0402 (1005)     316     =     1206 (3216)     53       105     =     0603 (1608)     32     =     1210 (3225)     55       F12     =     0508 (1220)/4cap     42     =     1808 (4520)     D1	E EIA (EIAJ) = 2208 (5720) = 5728 (2211) = 2220 (5750) 1 = 0405 (1012)/2cap 2 = 0508 (1220)/2cap
DIELECTRIC CODE —	
CODE EIA CODE  CG = C0G (NPO) X7S = X7S  X5R = X5R X6S = X6S (Option)  X7R = X7R Y5V = Y5V  Negative dielectric types are available on request.	
CAPACITANCE CODE ——————	
Capacitance expressed in pF. 2 significant digits plus number of zeros. For Values < 10pF, Letter R denotes decimal point, eg. $100000pF = 104$ $1.5pF = 1R5$ $0.1\mu F = 104$ $0.5pF = R50$ $4700pF = 472$ $100\mu F = 107$	
TOLERANCE CODE ————————————————————————————————————	
$A = \pm 0.05 pF$ $D = \pm 0.5 pF$ $J = \pm 5\%$ $Z = -2$ $B = \pm 0.1 pF$ $F = \pm 1 pF$ $K = \pm 10\%$ $C = \pm 0.25 pF$ $G = \pm 2\%$ $M = \pm 20\%$	0 to +80%
VOLTAGE CODE ————————————————————————————————————	
04 = 4VDC	DOVDC
TERMINATION CODE ——————	
A = Nickel Barrier	
PACKAGING CODE —	
C = Bulk Cassette H =	13" Reel Taping & 4mm Cavity pitch 7" Reel Taping & 2mm Cavity pitch 13" Reel Taping & 2mm Cavity pitch
OPTION —	

Thickness max value is indicated in CT series EX. 125  $\rightarrow$  1.25mm max

095 → 0.95mm max



# **High Dielectric Constant**

EIA Dielectric	Temperature Range	∆Cmax
X5R	–55 to 85°C	±15%
X7R	–55 to 125°C	±13%
X7S	–55 to 125°C	+22%
X6S	–55 to 105°C	±22%
Y5V	−30 to 85°C	-82 to +22%

# **Temperature Compensation Type**

Electric Code Value (pF)	1B/C0G	P∆ N150	R∆ N220	S∆ N330	T∆ N470	U∆ N750	SL +350 to -1000
0.5-2.7	CK	PK	RK	SK	TK	UK	SL
3.0-3.9	CJ	PJ	RJ	SJ	TJ	UJ	SL
4.0-9.0	СН	PH	RH	SH	TH	UJ	SL
≥10	CG	PH	RH	SH	TH	UJ	SL

 $K=\pm250ppm/^{\circ}C,\,J=\pm120ppm/^{\circ}C,\,H=\pm60ppm/^{\circ}C,\,G=\pm30ppm/^{\circ}C$ 

e.g.  $CG = 0\pm30 ppm/^{\circ}C$ ,  $PH = -150\pm60 ppm/^{\circ}C$ 

Note: All parts will be marked as "CG" but will conform to the above table.

### **Available Tolerances**

Dielectric materials, capacitance values and tolerances are available in the following combinations only:

EIA Dielectric	Standard Tolerance	Capacitance
	*4 A=±0.05pF	≤0.5pF
	*4 B=±0.1pF	≤5pF
	C=±0.25pF	
COG	D=±0.50pF	*2 <10pF
NTC *1	F=±1pF	
	G=±2%	>40-F
	J=±5%	≥10pF
	K=±10%	E12 Series
X5R	*3 K=±10%	FC Carias
X6R X7R	M=±20%	E6 Series
Y5V	Z=-20% to +80%	E3 Series

#### Note

#### **E Standard Number**

E3	E6	E12	E24 (C	ption)
	1.0	1.0	1.0	1.1
4.0	1.0	1.2	1.2	1.3
1.0	1.5	1.5	1.5	1.6
	1.5	1.8	1.8	2.0
	2.2	2.2	2.2	2.4
2.2	2.2	2.7	2.7	3.0
2.2	2.2	3.3	3.3	3.6
	3.3	3.9	3.9	4.3
	4.7	4.7	4.7	5.1
4.7	4.7	5.6	5.6	6.2
4.7	6.8	6.8	6.8	7.5
	0.0	8.2	8.2	9.1

<sup>\*1</sup> NTC : Negative Temperature Compensation types are available on request as shown on product pages.

<sup>\*2</sup> Nominal values below 10pF are available in the standard values of 0.5pF, 1.0pF, 1.5pF, 2.0pF, 3.0pF, 4.0pF, 5.0pF, 6.0pF, 7.0pF, 8.0pF, 9.0pF, 10pF.

<sup>\*3</sup> J =  $\pm$ 5% for X7R(X5R) is available on request.

<sup>\*4</sup> option



## **Features**

We offer a diverse product line ranging from ultra-compact (0.6 $\times$ 0.3 mm) to large (5.7 $\times$ 5.0 mm) components configured for a variety of temperature characteristics, rated voltages, and packages. We offer the choice and flexibility for almost any applications.

# **Application**

This standard type is ideal for use in a wide range of applications, from commercial to industrial equipment.

## **Temperature Compensation Dielectrics**

Size (r				CN (06	103 (03)					CM05 (1005)			CM (16	105 08)		CN (20	121 12)			CM316 (3216)	3	CM32 (3225)
Tempera Characte	ature ristics		CΔ		u	JΔ	SL		CΔ		UΔ	SL	C	ζΔ		C	Δ			CΔ		CΔ
Rated Volta	ce (pF)	10	16	25	16	25	25	16	25	50	50	50	50	100	16	25	50	100	25	50	100	50
R20 R50 1R0 1R5	0.2 0.5 1.0 1.5				А																	
	1.0 1.5 2.0 3.0 4.0 5.0																					
	5.0 6.0 7.0 8.0			A		Α.	Α .			в _	_ в _	_ в		_ с								
100 120	9.0																					
120	12 15 18																					
	22 27 33																					
	10 12 15 18 22 27 33 39 47 56 68 82 100		А																			
101 121	68 82 100	А																				
121	120 150 180 220																	D				
	220 270 330 390							В	В				С								D	
	390 470 560 680																D				D	
102 122	680 820 1000 1200																				D D	
	1500																Е				D	
	1800 2200 2700 3300															E				E	E	
	3900 4700															G				E		
l 103 1	5600 6800 8200 10000														G				E			H
1	12000 15000 18000																					

# Thickness and standard package quantity

Size	03	05	105	*105	21, 316, 32											
Thickness	A	В	C	С	D	E	F	G	Н		J	K	L			
(mm)	0.3±0.03	0.5±0.05	0.8±0.1	0.8±0.1	0.6±0.1	0.85±0.1	1.15±0.1	1.25±0.1	1.4max	1.6max	1.6±0.15	2.0±0.2	2.5±0.2			
Taping(180 dia reel)	15kp(P8)	10kp(P8)	4kp(P8)	8kp(P8)	4kp(P8)	4kp(P8)	3kp(E8)	3kp(E8)	3kp(E8)	2.5kp(E8)	2.5kp(E8)	2kp(E8)	1kp(E8)			
Taping(330 dia reel)		50kp(P8)	10kp(P8)	20kp(P8)	10kp(P8)	10kp(P8)	10kp(E8)	10kp(E8)	10kp(E8)	5kp(E8)	5kp(E8)	5kp(E8)				

Size	43, 55											
Thickness	J	K	L	M								
(mm)	1.6±0.15	2.0±0.2	2.5±0.2	2.8±0.2								
Taping(178 dia reel)	1kp(E12)	1kp(E12)	0.5kp(E12)	0.5kp(E12)								
Taping(330 dia reel)												

Note: P8 = 8mm width paper tape E8 = 8mm width plastic tape E12 = 12mm width plastic tape

<sup>\*</sup> Carrier tape 2mm pitch from one capacitor to another.



# **X5R Dielectric**

Size	e (mm)		CM03 (0603)				CM (10	105 05)						CM10: (1608	5 )					CN (20	121 12)		
	Voltage (VDC)	10	16	25	4	6.3	10	16	25	50	4	6.3	10	16	25	35	50	6.3	10	16	25	35	50
101	100																						
151	150 220 330			A																			
102	470 680 1000									В													
102 152	1500 2200 3300		Α														С						
103	4700 6800 10000	Α							В														
103 153	15000 22000 33000															С							D E
104	47000 68000 100000							В							С								G
154	150000 220000 330000				<i>777</i> 3	В	* B															G	
105	470000 680000 1000000				<b>B</b>								С	С							* G		
105 155	1500000 2200000 3300000										*1	*1							*1 *1	G			
106	4700000 6800000 10000000										*1							*1 *1 *2	*1				

Siz	ze (mm)				1316 216)						/132 (25)				CN (45		
	Voltage (VDC)	6.3	10	16	25	35	50	6.3	10	16	25	35	50	6.3	10	25	50
104	100000																
	220000						F										
405	470000					F											[
105	1000000											H	K				
	2200000				.a J							K					L.
106	4700000 10000000	*	* J	*2 J *2	*2				К		L						
	22000000	*2						. 4									
107	47000000 100000000							*2						* *2 M			

 $<sup>\</sup>ast$  Non standard specification, please contact us for further information.  $\hfill \square$  Optional Spec.

<sup>\*1</sup> Length(L, T) tolerance ±0.15 \*2 Length(L, T) tolerance ±0.2



# X7R, X7S Dielectric

Size	e (mm)	CM03 (0201)		CM (04	105 02)				CM (06	105 03)					CN (08	121 05)		
Capac	/oltage (VDC)	16	6.3	16	25	50	6.3	10	16	25	50	100	4	10	16	25	50	100
101 151	100 150 220 330	A																
102 152	470 680 1000					В					С	С						
152	1500 2200 3300																	
103 153	4700 6800 10000			В —	В													D E
153	15000 22000 33000		*							С							D E	G
104 154	47000 68000 100000		* B						С								G	
154	150000 220000 330000						*	С							G	G		
105 155	470000 680000 1000000						* * *							G				
155	1500000 2200000 3300000												* * *					
	4700000								1				*					

Siz	e (mm)				316 (06)						132 10)				CM43 (1812)		
	Voltage (VDC) citance (pF)	6.3	10	16	25	50	100	6.3	10	16	25	50	100	16	50	100	100
103	10000																
104	22000 47000 100000					F	F						н				
105	220000 470000 1000000			F	F	F	J				-	H	K L		J	L	
106	2200000 4700000 10000000	*2 *	* J							L	K				L		
	22000000							*									

# **Y5V Dielectric**

Siz	e (mm)	CM (02			CM05 (0402)			(06				CN (08				CM (12				CM (12	132 10)	
	Voltage (VDC) citance (pF)	6.3	10	16	25	50	10	16	25	50	10	16	25	50	10	16	25	50	10	16	25	50
102 472	1000 2200 4700		Α																			
103	10000 22000 47000	Α		В	В	В				С												
104	100000 220000 470000							С	С			E	D E	E G				F				
105	1000000 2200000 4700000						С				G	G	G			F	F					H
106 476	10000000 22000000 47000000														J	J			K	J	7	

# Thickness and standard package quantity

Size	03	05	105	*105					21, 316, 32				
Thickness	Α	В	C	С	D	E	F	G	H		J	K	L
(mm)	0.3±0.03	0.5±0.05	0.8±0.1	0.8±0.1	0.6±0.1	0.85±0.1	1.15±0.1	1.25±0.1	1.4max	1.6max	1.6±0.15	2.0±0.2	2.5±0.2
Taping(180 dia reel)	15kp(P8)	10kp(P8)	4kp(P8)	8kp(P8)	4kp(P8)	4kp(P8)	3kp(E8)	3kp(E8)	3kp(E8)	2.5kp(E8)	2.5kp(E8)	2kp(E8)	1kp(E8)
Taping(330 dia reel)		50kp(P8)	10kp(P8)	20kp(P8)	10kp(P8)	10kp(P8)	10kp(E8)	10kp(E8)	10kp(E8)	5kp(E8)	5kp(E8)	5kp(E8)	

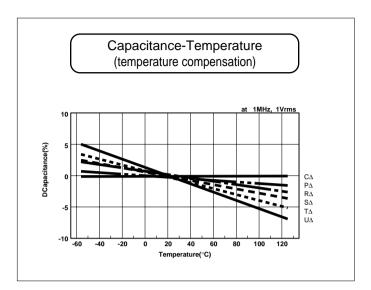
Size		43	, 55	
Thickness (mm)	J	K		M
, ,	1.6±0.15	2.0±0.2	2.5±0.2	2.8±0.2
Taping(178 dia reel)	1kp(E12)	1kp(E12)	0.5kp(E12)	0.5kp(E12)
Taping(330 dia reel)				

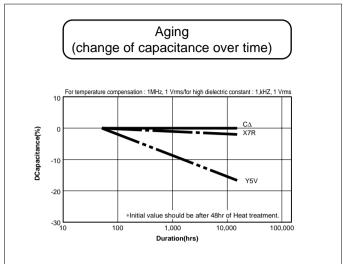
Note: P8 = 8mm width paper tape E8 = 8mm width plastic tape E12 = 12mm width plastic tape

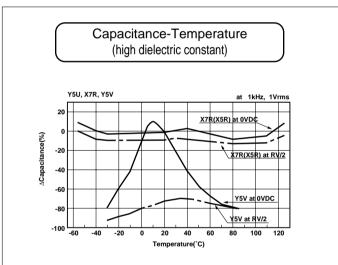
<sup>\*</sup> Only X7S available \*2 Length(W, T) Tolerance ±0.2, X7S available

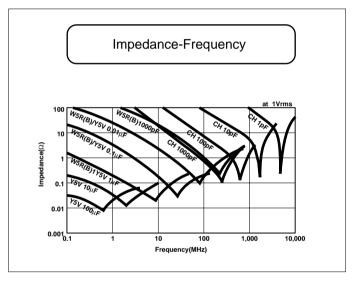
<sup>\*</sup> Carrier tape 2mm pitch from one capacitor to another.

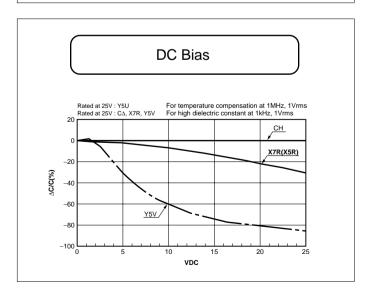


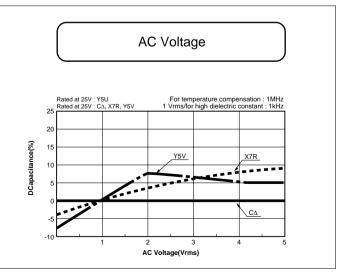












Please verify individual characteristics at the design stage to ensure total suitability



# Test conditions and Specification for Temperature Compensation type(C\* to U\* • SL characteristics)

Tes	t Items	Specification (C: nominal capacitance)	Test Conditions		
Capacitance	· Value	Within tolerance	C≤1000pF 1MHz±10% 0.5 to		
Q		C≥30pF: Q≥1000	C>1000pF 1kHz±10% 5Vrms		
		C<30pF: Q≥400+20C			
Insulation re	esistance (IR)(*6)	10,000M $\Omega$ or 500M $\Omega$ •μF min, whichever is less	Measured after the rated voltage is applied for one minute at normal room temperature and humidity. (*4)		
Dielectric R	esistance (*6)	No problem observed	(*1) Apply 3 times of the rated voltage for 1 to 5 seconds		
Appearance		No problem observed	Microscope(10×magnification)		
Termination	strength (*2)	No problem observed	Apply a sideward force of 500g(5N) (*7) to a PCB-moun sample.		
Bending str	ength (*2)	No mechanical damage at 1mm bent	Glass epoxy PCB (t=1.6mm); fulcrum Spacing: 90mm; for 10 seconds.		
Vibration	Appearance	No significant change is detected.	Vibration frequency: 10 to 55(Hz)		
test	Δ <b>C</b>	Within tolerance	Amplitude: 1.5mm		
		C≥30pF: Q≥1000	Sweeping condition: 10→55→10Hz/min In X, Y and Z directions:		
	Q	C<30pF: Q≥400+20C	2 hours each Total 6 hours		
Soldering	Appearance	No significant change is detected.	Soak the sample in 260°C±5°C		
heat resistance	ΔC	±2.5% or ±0.25pF max, whichever is larger.	solder for 10±0.5seconds and place in a room at normal temperature		
		C≥30pF: Q≥1000	and humidity; measure after 24±2hours.		
	Q	C<30pF: Q≥400+20C	(Preheating Conditions)		
	<b>IR</b> (*6)	10,000MΩ or 500MΩ•μF min, whichever is smaller	Order         Temperature         Time           1         80 to 100°C         2minutes		
	Withstand voltage (*6)	Resists without problem	2 150 to 200°C 2minutes		
Solderability	1	Ni/Br termination: 90% min	Sn63 Solder         235±5°C         2±0.5sec.           Sn-3Ag-0.5Cu         245±5°C         3±0.5sec.		
Temperature	Appearance	No significant change is detected.	(Cycle)		
cycle (*3)	ΔC	±2.5% or ±0.25pF max, whichever is larger.	Normal room temperature (3min)→ Lowest operation temperature (30min)→		
	0	C≥30pF: Q≥1000	Normal room temperature (3min)→		
	Q	C<30pF: Q≥400+20C	Highest operation temperature (30min)→		
	<b>IR</b> (*6)	10,000MΩ or 500MΩ•μF min, whichever is samller	After five cycles (*3), measure after		
	Withstand voltage (*6)	Resists without problem	24±2hours.		
Humidity	Appearance	No significant change is detected.	Measure the test sample after storing it		
test (*5)	ΔC	±7.5% or ±0.75pF max, whichever is larger.	24±2hours at a temperature of 40°C±2°C and a relative humidity of 90-95% Rh.		
	Q	C≥30pF: Q≥200	for 500+24/–0hours.		
		C<30pF: Q≥100+10C/3			
	<b>IR</b> (*6)	500MΩ or 25MΩ•μF min, whichever is smaller			
High- temperature	Appearance	No significant change is detected.	After applying (*1) twice of the rated volt at a temperature of 125±3°C for 1000+48/–0hours, measure the sample after storing 24±2hours.		
	ΔC	±3% or ±0.3pF max, whichever is larger.			
with		C≥30pF: Q≥350			
with loading	Q	0≥30pr. Q≥330 10pF≤C<30pF: Q≥275+5C/2 C<10pF: Q≥200+10C			

<sup>\*1</sup> For the CF series, use 1.5 times when the rated voltage is 250V; use/1.2 times when the rated voltage exceeds 630V.

<sup>\*2</sup> Except CT series

<sup>\*3</sup> Different specification for Nickel Barrier termination DN/DR series. (Alumina Substrate)

Apply 500V for 1minite in case the rated voltage is 1000V or higher.

<sup>\*5</sup> Except CF series.

<sup>\*6</sup> The charge and discharge current of the capacitor must not exceed 50mA.

<sup>\*7 2</sup>N at 0201 Size



# Test conditions and Specification for High Dielectric Type (X5R, X7R, Y5V)

Tos	t Items	Specifi		Test Condition		
162	t items	X7R/X5R	Y5V			
Capacitance	e Value	Within tolerance		Do previous treatment (*8, *14)  Capacitance Fire Vol		
tanδ(%)		2.5%max, 3.5%max (*2), 7.0%max (*12) 5.0%max (*3), 7.5%max (*17)	5.0%max, 7.0%max (*13) 9.0%max (*4), 12.5%max (*5)	C≤10μF 1kHz±10% 1.0±0.1Vrms C>10μF 120Hz±10% 0.5±0.1Vrms		
Insulation re	esistance (IR) (*15)	10,000MΩ or 500MΩ•μF min, wh	nichever is less	Measured after the rated voltage is applied for 2minutes at normal room temperature and humidity. (*10)		
Dielectric R	esistance (*15)	No problem observed		(*1) Apply 2.5 times of the rated voltage for 1 to 5 seconds		
Appearance		No problem observed		Microscope(10×magnification)		
Termination	strength (*6)	No problem observed		Apply a sideward force of 500g(5N) (*16) to a PCB-mounted sample.		
Bending str	ength test (*6)	No problem observed at 1mm be	ent	Glass epoxy PCB (t=1.6mm); fulcrum Spacing: 90mm; for 10 seconds.		
Vibration	Appearance	No significant change is detected	d.	Vibration frequency: 10 to 55(Hz)  Amplitude: 1.5mm		
test	ΔC	Within tolerance		Sweeping condition: 10→55→10Hz/min		
	tanδ(%)	Satisfies the initial value.		In X, Y and Z directions: 2 hours each Total 6 hours		
Soldering heat	Appearance	No significant change is detected	d.	Do previous treatment (*8) Soak the sample in 260°C±5°C		
resistance	ΔC	Within ±7.5%	Within ±20%	solder for 10±0.5seconds and place in a room at normal temperature		
	tanδ(%)	Satisfies the initial value.		and humidity; measure after 48±4hours. (Preheating Conditions)		
	IR (*15)	10,000MΩ or 500MΩ•μF min, wh	nichever is smaller	Order Temperature Time		
	Withstand voltage (*15)	Resists without problem		1 80 to 100°C 2minutes 2 150 to 200°C 2minutes		
Solderabilit	у	Ni/Br termination: 90% min	Soaking Condition           Sn63 Solder         235±5°C         2±0.5sec.           Sn-3Ag-0.5Cu         245±5°C         3±0.5sec.			
Temperature	Appearance	No significant change is detected	d.	Do previous treatment (*8) (Cycle)		
cycle (*7)	ΔC	Within ±7.5%	Within ±20%	Normal room temperature (3min)→ Lowest operation temperature (30min)→		
	tanδ(%)	Satisfies the initial value.		Normal room temperature (3min)→ Highest operation temperature (30min)→		
	IR (*15)	10,000MΩ or 500MΩ•μF min, wh	nichever is smaller	After five cycles (*7), measure after 48±4hours.		
	Withstand voltage (*15)	Resists without problem		40±4110u15.		
Humidity test (*11)	Appearance	No significant change is detected	d.	Do previous treatment (*9)  After storing it at a temperature of		
test (*ii)	ΔC	Within ±12.5%	Within ±30%	40°C±2°C and a relative humidity of		
	tanδ(%)	200% max of initial value	150% max of initial value	90-95% for 500+24/–0hours, measure the sample after storing 48±4hours.		
	IR (*15)	500MΩ or 25MΩ•μF min, whiche	ever is smaller			
High- temperature	Appearance	No significant change is detected	Do previous treatment (*9)  After applying twice (*18) of the rated			
with loading	ΔC	Within ±12.5%	Within ±30%	voltage at the highest operating temperature		
5	tanδ(%)	200% max of initial value	150% max of initial value	for 1000+48/–0hours, measure the sample after storing 48±4hours.		
	IR (*15)	1,000MΩ or 50MΩ•μF min, whicl	hever is smaller	-		
Use 1.5 times whe	en the rated voltage is 250V	or over	*10 For the CE series over 10001/ appl	ly 500V for 1 minutes at room ambient.		

<sup>1</sup> Use 1.5 times when the rated voltage is 250V or over.
Use 1.2 times when the rated voltage is 630V or over.
2 Apply to XSR 35V type, X7R 16V/25V type.
3 Apply to XSR 16V/25V type, X7R/X75 6.3V/10V type.
4 Apply to Y5V 16V type, CM32Y5V335 to 106 (25V Type).
5 Apply to Y5V 16V type, CM32Y5V335 to 106 (25V Type).
6 Exclude CT series with thickness of less than 0.66mm and CA series.
7 Different Specification for Nickel Barrier termination DN/DR series. (Alumina Substrate)
8 Keep specimen at 150°C+0/-10°C for one hour, leave specimen at room ambient for 48±4 hours.
9 Apply the same test condition for one hour, then leave the specimen at room ambient for 48±4 hours.

<sup>\*10</sup> For the CF series over 1000V, apply 500V for 1 minutes at room ambient.

\*11 Except CF series.

\*12 Apply to X5R 10V type, X7S 4V type.

\*13 Apply to 25V series of CM105Y5V154 over, CM21Y5V105 over, 316Y5V155 over.

\*14 Measurement condition 1kHz, 1Vrms for Y5V, C < 47µF type.

\*15 The charge/discharge current of the capacitor must not exceed 50mA.

\*16 2N at 0201 Size

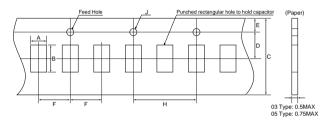
 <sup>110 2</sup> IN at 0.201 31.26
 117 Apply to XSR 4V and 6.3V type.
 \*18 Use 1.5times when the rated voltage is 4V/6.3V/10V/250V and 100V (32X7R474/43X7R105/55X7R105). Use 1.2times when the rated voltage is 630V or over.



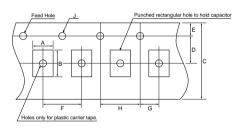
# **Tape and Reel**

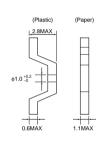
• Reel

F=2mm(03, 05, 105 Type)

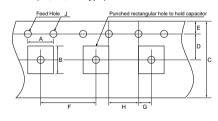


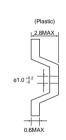
F=4mm(105, D11, D12, F12, F13, 21, 316, 32, 42, 52 Type)

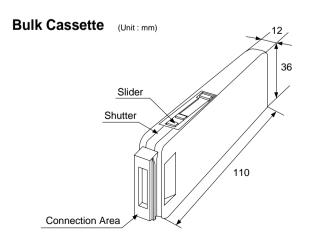




F=8mm(43, 53, 55 Type)







# Reel (code: T)

Code Reel	Α	В	С	D
7-inch Reel (CODE : T, H)	178±2.0	φ60min	13±0.5	21±0.8
13-inch Reel (CODE : L, N)	330±2.0	φ100±1.0	13±0.5	21±0.6
Code Reel	E	<b>W</b> 1	W <sub>2</sub>	R
7-inch Reel (CODE : T, H)	2.0±0.5	10.0±1.5	16.5max	1.0
13-inch Reel (CODE : L, N)	∠.0±0.5	9.5±1.0	TO.SITIAX	1.0

\*Carrier tape width 8mm. For size 42(1808) or over, Tape width 12mm and W1 : 14±1.5, W2 : 18.4mm max

# **Carrier Tape**

(	Uni	+٠	m	m

(Unit : mm)

Туре	Α	В	F
03 (0.6×0.3)	0.37±0.03	0.67±0.03	2.0±0.05
05 (1.0×0.5)	0.65±0.1	1.15±0.1	2.0±0.05
105 (1.6×0.8)	1.0±0.2	1.8±0.2	4.0±0.1
D11 (1.37×1.0)	1.15±0.1	1.55±0.1	4.0±0.1
D12 (1.25×2.0)	1.5±0.2	2.3±0.2	4.0±0.1
F12 (1.25×2.0)	1.5±0.2	2.3±0.2	4.0±0.1
F13 (1.6×3.2)	2.0±0.2	3.6±0.2	4.0±0.1
21 (2.0×1.25)	1.5±0.2	2.3±0.2	4.0±0.1
316 (3.2×1.6)	2.0±0.2	3.6±0.2	4.0±0.1
32 (3.2×2.5)	2.9±0.2	3.6±0.2	4.0±0.1
42 (4.5×2.0)	2.4±0.2	4.9±0.2	4.0±0.1
43 (4.5×3.2)	3.6±0.2	4.9±0.2	8.0±0.1
52 (5.7×2.0)	2.4±0.2	6.0±0.2	4.0±0.1
53 (5.7×2.8)	3.2±0.2	6.0±0.2	8.0±0.1
55 (5.7×5.0)	5.3±0.2	6.0±0.2	8.0±0.1

(Unit: mm)

F	Carrier Tape	С	D	E	G	н	J
2.0 ±0.05	8mm Paper	0.0	2.5				
4.0 ±0.1	8mm Plastic	8.0 ±0.3	3.5 ±0.05	1.75 ±0.1	2.0 ±0.05	4.0 ±0.1	1.5 +0.1/–0
8.0 ±0.1	12mm Plastic	12.0 ±0.3	5.5 ±0.05	±0.1	±0.00	±0.1	10.1/-0



## **Circuit Design**

- 1. Once application and assembly environments have been checked, the capacitor may be used in conformance with the rating and performance which are provided in both the catalog and the specifications. Use exceeding that which is specified may result in inferior performance or cause a short, open, smoking, or flaming to occur, etc.
- 2. Please consult the manufacturer in advance when the capacitor is used in devices such as: devices which deal with human life, i.e. medical devices; devices which are highly public orientated; and devices which demand a high standard of liability.
  - Accident or malfunction of devices such as medical devices, space equipment and devices having to do with atomic power could generate grave consequence with respect to human lives or, possibly, a portion of the public. Capacitors used in these devices may require high reliability design different from that of general purpose capacitors.
- 3. Please use the capacitors in conformance with the operating temperature provided in both the catalog and the specifications.
  - Be especially cautious not to exceed the maximum temperature. In the situation the maximum temperature set forth in both the catalog and specifications is exceeded, the capacitor's insulation resistance may deteriorate, power may suddenly surge and short-circuit may occur.
  - The capacitor has a loss, and may self-heat due to equivalent series resistance when alternating electric current is passed therethrough. As this effect becomes especially pronounced in high frequency circuits, please exercise caution.
  - When using the capacitor in a (self-heating) circuit, please make sure the surface of the capacitor remains under the maximum temperature for usage. Also, please make certain temperature rises remain below 20°C.
- 4. Please keep voltage under the rated voltage which is applied to the capacitor. Also, please make certain the peak voltage remains below the rated voltage when AC voltage is super-imposed to the DC voltage.
  - In the situation where AC or pulse voltage is employed, ensure average peak voltage does not exceed the rated voltage.
  - Exceeding the rated voltage provided in both catalog and specifications may lead to defective withstanding voltage or, in worst case situations, may cause the capacitor to smoke or flame.
- 5. When the capacitor is to be employed in a circuit in which there is continuous application of a high frequency voltage or a steep pulse voltage, even though it is within the rated voltage, please inquire to the manufacturer.
  - In the situation the capacitor is to be employed using a high frequency AC voltage or a extremely fast rising pulse voltage, even though it is within the rated voltage, it is possible capacitor reliability will deteriorate.
- 6. It is a common phenomenon of high-dielectric products to have a deteriorated amount of static electricity due to the application of DC voltage.

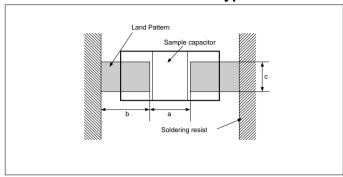
  Due caution is necessary as the degree of deterioration varies depending on the quality of capacitor materials, capacity, as well as the load voltage at the time of operation.
- 7. Do not use the capacitor in an environment where it might easily exceed the respective provisions concerning shock and vibration specified in the catalog and specifications.
  - In addition, it is a common piezo phenomenon of high dielectric products to have some Voltage due to vibration or to have noise due to Voltage change. Please contact sales in such case.
- 8. If the electrostatic capacity value of the delivered capacitor is within the specified tolerance, please consider this when designing the respective product in order that the assembled product function appropriately.

#### Storage

- 1. If the component is stored in minimal packaging (a heat-sealed or chuck-type plastic bag), the bag should be kept closed. Once the bag has been opened, reseal it or store it in a desiccator.
- 2. Keep storage place temperature +5 to +35 degree C, humidity 45 to 70% RH.
- 3. The storage atmosphere must be free of gas containing sulfur and chlorine. Also, avoid exposing the product to saline moisture. If the product is exposed to such atmospheres, the terminals will oxidize and solderability will be effected.
- 4. Precautions 1)-3) apply to chip capacitors packaged in carrier tapes and bulk cases.
- 5. The solderability is assured for 12 months from our shipping date (six months for silver palladium) if the above storage precautions are followed.
- 6. Chip capacitors may crack if exposed to hydrogen (H2) gas while sealed or if coated with silicon, which generates hydrogen gas.



# Dimensions for recommended typical land



When mounting the capacitor to the substrate, it is important to consider carefully that the amount of solder (size of fillet) used has a direct effect upon the capacitor once it is mounted.

- a) The greater the amount of solder, the greater the stress to the elements. As this may cause the substrate to break or crack, it is important to establish the appropriate dimensions with regard to the amount of solder when designing the land of the substrate.
- b) In the situation where two or more devices are mounted onto a common land, separate the device into exclusive pads by using soldering resist

#### Standard

(Unit:mm)

Size	L×W	а	b	С
03	0.6×0.3	0.20 to 0.30	0.25 to 0.35	0.30 to 0.40
05	1.0×0.5	0.30 to 0.50	0.35 to 0.45	0.40 to 0.60
105	1.6×0.8	0.70 to 1.00	0.80 to 1.00	0.60 to 0.80
21	2.0×1.25	1.00 to 1.30	1.00 to 1.20	0.80 to 1.10
316	3.2×1.6	2.10 to 2.50	1.10 to 1.30	1.00 to 1.30
32	3.2×2.5	2.10 to 2.50	1.10 to 1.30	1.90 to 2.30
42	4.5×2.0	2.50 to 3.20	1.80 to 2.30	1.50 to 1.80
43	4.5×3.2	2.50 to 3.20	1.80 to 2.30	2.60 to 3.00
52	5.7×2.0	4.20 to 4.70	2.00 to 2.50	1.50 to 1.80
53	5.7×2.8	4.20 to 4.70	2.00 to 2.50	2.20 to 2.60
55	5.7×5.0	4.20 to 4.70	2.00 to 2.50	4.20 to 4.70

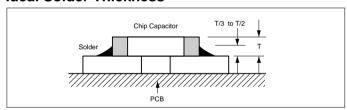
<sup>\*</sup> CA series : Please refer Page 19.

### **DN/DR Automotive Series**

(Unit:mm)

Size	L×W	а	b	С
105	1.6×0.8	0.60 to 0.90	0.80 to 1.00	0.70 to 1.00
21	2.0×1.25	0.90 to 1.20	0.80 to 1.20	0.90 to 1.40
316	3.2×1.6	1.40 to 1.90	1.00 to 1.30	1.30 to 1.80

### **Ideal Solder Thickness**



#### Typical mounting problems

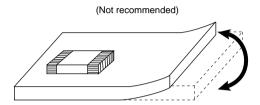
Item	Not recommended example	Recommended example/Separated by solder resist	
Multiple parts mount		Solder resist	
Mount with leaded parts	Leaded parts	Solder resist  Leaded parts	
Wire soldering after mounting	Soldering iron Wire	Solder resist	
Overview	Solder resist	Solder resist	

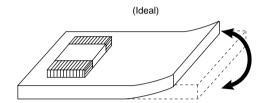


## **Mounting Design**

The chip could crack if the PCB warps during processing after the chip has been soldered.

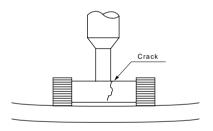
## Recommended chip position on PCB to minimize stress from PCB warpage

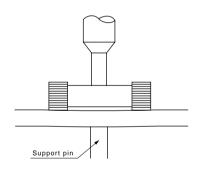




## **Actual Mounting**

- 1) If the position of the vacuum nozzle is too low, a large force may be applied to the chip capacitor during mounting, resulting in cracking.
- 2) During mounting, set the nozzle pressure to a static load of 100 to 300 gf.
- 3) To minimize the shock of the vaccum nozzle, provide a support pin on the back of the PCB to minimize PCB flexture.





- 4) When the positioning hook begins to wear, unstable mechanical shock may be applied to the chip capacitor, resulting in cracking.
- 5) To reduce the possibility of chipping and cracks, minimize vibration to chips stored in a bulk case.
- 6) The discharge pressure must be adjusted to the part size. Verify the pressure during setup to avoid fracturing or cracking the chips capacitors.

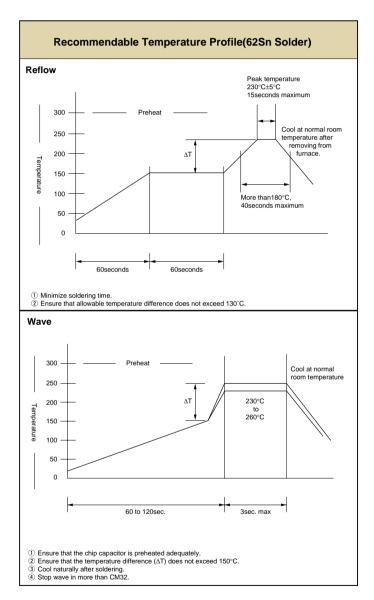
#### **Resin Mold**

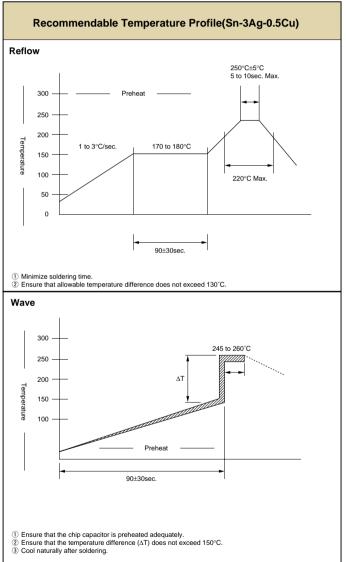
- 1) If a large amount of resin is used for molding the chip, cracks may occur due to contraction stress during curing. To avoid such cracks, use a low shrinkage resin.
- 2) The insulation resistance of the chip will degrade due to moisture absorption. Use a low moisture absorption resin.
- 3) Check carefully that the resin does not generate a decomposition gas or reaction gas during the curing process or during normal storage. Such gases may crack the chip capacitor or damage the device itself.



## **Soldering Method**

- 1) Ceramic is easily damaged by rapid heating or cooling. If some heat shock is unavoidable, preheat enough to limit the temperature difference (Delta T) to within 130 degree Celsius.
- 2) The product size 1.0×0.5mm to 3.2×1.6mm can be used in reflow and wave soldering, and the product size of over 3.2×2.5mm, 0.6×0.3mm, and capacitor arrays can be used in reflow.
  - Circuit shortage and smoking can be created by using capacitors which are used neglecting the above caution.
- 3) Please see our recommended soldering conditions.
  - Please contact us if you use lead free solder because the peak temperature of lead free is different from non-lead free.





# Sodering iron

1) Temperature of iron chip 350°C max

2) Wattage 30W max

3) Tip shape of soldering iron \$\phi 3.0mm max

4) Soldering Time

3sec. max

5) Cautions

a) Pre-heating is necessary Rapid heating must be avoided.
 Delta T≤130°C.

- b) Avoid direct touching to capacitors.
- c) Avoid rapid cooling after soldering. Natural cooling is recommended.



Компания «ЭлектроПласт» предлагает заключение долгосрочных отношений при поставках импортных электронных компонентов на взаимовыгодных условиях!

### Наши преимущества:

- Оперативные поставки широкого спектра электронных компонентов отечественного и импортного производства напрямую от производителей и с крупнейших мировых складов;
- Поставка более 17-ти миллионов наименований электронных компонентов;
- Поставка сложных, дефицитных, либо снятых с производства позиций;
- Оперативные сроки поставки под заказ (от 5 рабочих дней);
- Экспресс доставка в любую точку России;
- Техническая поддержка проекта, помощь в подборе аналогов, поставка прототипов;
- Система менеджмента качества сертифицирована по Международному стандарту ISO 9001:
- Лицензия ФСБ на осуществление работ с использованием сведений, составляющих государственную тайну;
- Поставка специализированных компонентов (Xilinx, Altera, Analog Devices, Intersil, Interpoint, Microsemi, Aeroflex, Peregrine, Syfer, Eurofarad, Texas Instrument, Miteq, Cobham, E2V, MA-COM, Hittite, Mini-Circuits, General Dynamics и др.);

Помимо этого, одним из направлений компании «ЭлектроПласт» является направление «Источники питания». Мы предлагаем Вам помощь Конструкторского отдела:

- Подбор оптимального решения, техническое обоснование при выборе компонента;
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



#### Как с нами связаться

**Телефон:** 8 (812) 309 58 32 (многоканальный)

Факс: 8 (812) 320-02-42

Электронная почта: <u>org@eplast1.ru</u>

Адрес: 198099, г. Санкт-Петербург, ул. Калинина,

дом 2, корпус 4, литера А.